



PATENT
YOR19960184 IBM-219

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	D.Y.Shih, et al.
Serial Number	:	09/254,769
Filing Date	:	March 11, 1999
Examiner	:	V. Nguyen
Group Art Unit	:	2829
For	:	WAFER SCALE HIGH DENSITY PROBE ASSEMBLY , APPARATUS FOR USE THEREOF AND METHODS OF FABRICATION THEREOF

Honorable Commissioner of Patents
and Trademarks
Post Office Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend the above-identified application as follows:

IN THE CLAIMS:

Cancel without prejudice Claims 8, 32, 34-45, 49-51 and 60.

REMARKS

Applicants have canceled Claims 8, 32, 34-45, 49-51 and 60 and reserve the right to refile them in a divisional application. Accordingly please pass this case to issue including allowed